Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (Currently amended): A library core for embedded passive components, comprising:

an insulating core layer having an upper surface and a lower surface opposed to the upper surface, and formed with a plurality of openings penetrating therethrough, wherein the openings are filled with capacitive materials therein; and

a plurality of conductive traces formed from electrically conductive layers as a whole on the core layer by pattering, and formed over the upper and lower surfaces of the core layer and fully covered the capacitive materials, wherein the conductive traces are electrically interconnected to the capacitive materials as well as partly used as parallel sheets onto the capacitive materials to form capacitors embedded in the core layer.

Claims 2-6 (Canceled)

Claim 7 (Original): The library core for embedded passive components of claim 1, wherein the core layer is formed with a plurality of conductive vias for electrically interconnecting the electrically conductive layers on the upper and lower surfaces of the core layer.

Claim 8 (Previously presented): The library core for embedded passive components of claim 1, wherein the library core with the patterned conductive traces is fabricated in a semiconductor packaging substrate or printed circuit board for enhancing performances of electrical characteristics.

Claim 9 (Previously presented): The library core for embedded passive components of claim 1, wherein the library core with the patterned conductive traces is formed with an insulating layer over the conductive traces on the core layer and formed at least one circuit layer on the insulating layer so as to form a multi-layer circuit board.

Claim 10 (Original): The library core for embedded passive components of claim 9, wherein the multi-layer circuit board is fabricated in a flip-chip semiconductor packaging substrate.

Claim 11 (Original): The library core for embedded passive components of claim 9, wherein the multi-layer circuit board is fabricated in a wire-bonding semiconductor packaging substrate.

Claim 12 (Currently amended): A method for forming ~~an electronic device on~~ a library core for embedded passive components, comprising the steps of:

providing an insulating core layer having an upper surface and a lower surface opposed to the upper surface, wherein the core layer is formed with a plurality of openings penetrating therethrough, allowing the openings to be filled with capacitive materials, and electrically conductive layers ~~are~~ formed as a whole on the core layer are over the upper and lower surfaces of the core layer respectively; and

patterning the electrically conductive layers respective on the upper and lower surfaces of the core layer to form a plurality of conductive traces for electrically interconnecting the capacitive materials contained in the openings of the core layer as well as partly used as parallel sheets onto the capacitive materials to thereby form the library core with ~~the~~ embedded capacitor~~; and~~

~~mounting and electrically connecting the library core with the embedded capacitors to the electronic device~~.

Claims 13-16 (Canceled)

Claim 17 (Original): The method of claim 12, wherein the core layer is formed with a plurality of conductive vias for electrically interconnecting the conductive traces on the upper and lower surfaces of the core layer.

Claim 18 (Canceled)

Claim 19 (New): The library core for embedded passive components of claim 1, wherein the capacitive materials is polymeric materials, ceramic materials, or polymers formed by ceramic powders.

Claim 20 (New): The method of claim 12, wherein the capacitive materials is polymeric materials, ceramic materials, or polymers formed by ceramic powders.